GL390/GL390V

■ Features

1. Thin bow type resin mold package (Resin area : 2.0 x 3.1 x 5.2 mm)

2. Low peak forward voltage (GL390V)

VFM: TYP. 1.9V at IFM=0.5A

■ Applications

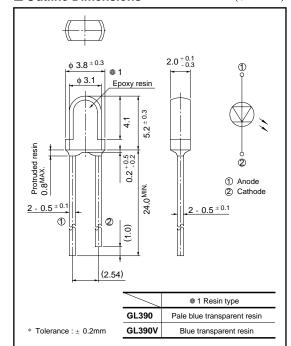
1. Cameras

2. Infrared remote controllers

Thin Bow Type Resin Mold Package Infrared Emitting Diodes

■ Outline Dimensions

(Unit: mm)



■ Model Lineup

Model	GL390	GL390V		
Radiant intensity (mW/sr)	TYP. 13	TYP. 16		
Half intensity angle (°)	TYP. ± 18			

■ Absolute Maximum Ratings

 $(Ta=25^{\circ}C)$

Parameter	ameter Symbol Rating		Unit	
Forward current	I_F	60	mA	
*1Peak forward current	I_{FM}	1	A	
Reverse voltage	V_R	6	V	
Power dissipation	P	150	mW	
Operating temperature	T opr	- 25 to 85	°C	
Storage temperature	T stg	- 40 to 85	°C	
*2Soldering temperature	T sol	260	°C	

^{*1} Pulse width <= 100 µ s, Duty ratio=0.01

^{*2} For 3 seconds at the position of 2.6 mm from the resin edge



■ Electro-optical Characteristics

(Ta=25 °C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Forward voltage		VF	$I_F = 50 \text{mA}$	-	1.3	1.5	V
Peak forward voltage	GL390	V _{FM}	$I_{\text{FM}} = 0.5A$	-	2.2	3.5	V
	GL390V			-	1.9	3.0	
Reverse current		I_R	$V_R = 3V$	-	-	10	μΑ
*3 Radiant intensity	GL390	IE	$I_F = 50 \text{mA}$	7	13	-	mW/sr
	GL390V			9	16	-	
Peak emission wavelength		λP	$I_F = 5mA$	-	950	-	nm
Half intensity wavelength		Δλ	$I_F = 5mA$	-	45	-	nm
Terminal capacitance	GL390	Ct	$V_R = 0 f = 1MHz$	-	70	-	pF
	GL390V			-	50	-	
Response frequency		fc		-	300	-	kHz
Half intensity angle		Δθ	$I_F = 20 \text{mA}$	-	± 18	-	۰

^{*3} I E: Value obtained by converting the value in power of radiant fluxes emitted at the solid angle of 0.01 sr (steradian) in the direction of mechanical axis of the lens portion into 1 sr or all those emitted from the light emitting diode.

Fig. 1 Forward Current vs. Ambient Temperature

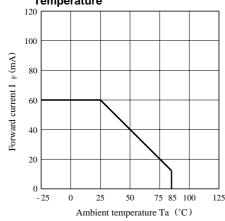


Fig. 2 Peak Forward Current vs. Duty Ratio

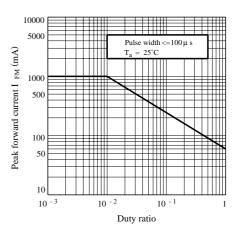




Fig. 3 Spectral Distribution

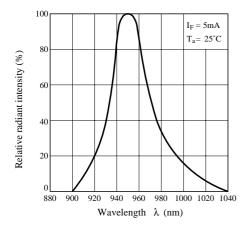


Fig. 5-1 Forward Current vs. Forward Voltage (GL390)

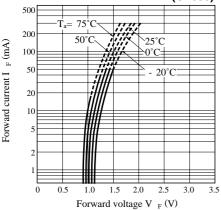


Fig. 6 Relative Radiant Flux vs. Ambient Temperature

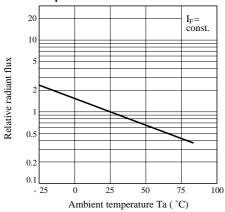


Fig. 4 Peak Emission Wavelength vs.
Ambient Temperature

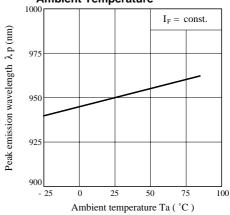


Fig. 5-2 Forward Current vs. Forward Voltage

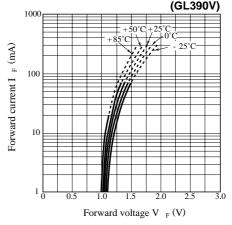


Fig. 7 Radiant Intensity vs. Forward Current

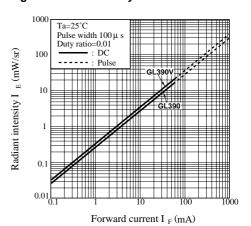


Fig. 8-1 Radiation Diagram (Horizontal Direction)

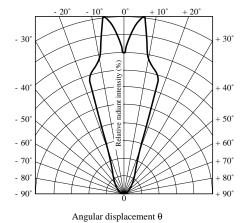
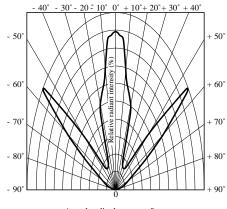


Fig. 8-2 Radiation Diagram (Vertical Direction)



Angular displacement θ

• Please refer to the chapter "Precautions for Use". (Page 78 to 93)

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 - Alarm equipment
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